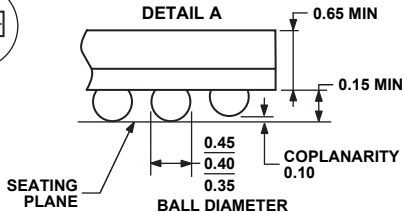
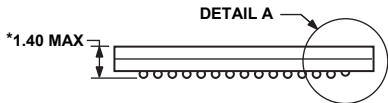
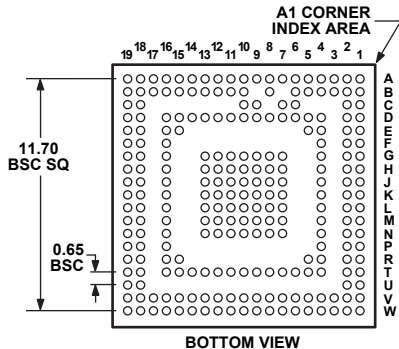
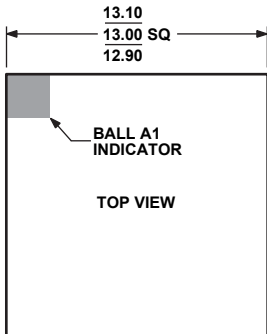


**237-Ball Chip Scale Package Ball Grid Array [CSP\_BGA]  
(BC-237-2)**

Dimensions shown in millimeters



\*COMPLIANT TO JEDEC STANDARDS MO-225  
WITH THE EXCEPTION TO PACKAGE HEIGHT.